

SCANNING ACOUSTIC MICROSCOPY

VUE 400-P

DETECTS WHAT OTHERS MISS.

PVA TePla

Our high-resolution scanning acoustic microscope for package inspection and failure analysis – reliably detecting voids, disbonds, cracks, delaminations, and internal defects, fully non-destructive, with micron-level accuracy.



FEATURES AT A GLANCE



Micron-level accuracy

Quad Linear Servo drive, max velocity 1,500 mm/s, accuracy & repeatability ± 0.5 micron – maintenance-free scan axis



ODIS Software – powered by intelligence

Advanced data-driven analysis: void gating, cluster analysis, threshold mapping, realtime A-scan, B-scan & SLICE, and Time-of-light & thickness measurements



Comprehensive scanning modes

A-Scan, B-Scan, C-Scan, TX-Scan, 3D imaging, SALI, Dual Gate, Counterfeit Detection and more – all in one system



Application-specific transducers

Engineered for highest resolution – multiple transducer designs for enhanced scan capability across the full ultrasonic spectrum



Large scan & step coverage

Scan Length 400 mm · Step Length 380 mm · C-Scan Area 360×350 mm · T-Scan Area 360×220 mm



Fully non-destructive process

Acoustic imaging preserves sample integrity – ideal for high-value and production-critical components



MORE INFORMATION? – GET IN CONTACT!

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TECHNICAL PARAMETERS



Every detail matters. The VUE 400-P-NexGen is engineered for high-precision acoustic inspection — trusted across energy, aerospace & defense, automotive, semiconductor, and medical industries.

SPECIFICATIONS	
Scan Length	400 mm
Step Length	380 mm
Focus Length	35 mm
C-Scan Area T-Scan Area	360 x 350 mm ² 360 x 220 mm ²
Motor Max Velocity Accuracy	Quad Linear Servo 1,500 mm/s +/- 0.5 micron
Scan Axis	Maintenance Free
Instrumentation	■ Digital Pulser Receiver ■ Ultrasonic Digitizer (Max 12 GHz)
Customer Interface	Dual 22" HD LED Monitors
UX Elements	■ HD LED Lighting ■ Stainless Steel Tank
Fixtures	JEDEC Tray Fixture (single or dual)
Dimensions	889 x 915 x 1193 mm (WxDxH)
Weight	250 kg
SCANNING MODES	
A-Scan	Real-time waveform display & capture
B-Scan / Focus B / Sub B / Cross B	Cross-section & slice imaging
C-Scan	Planar top-down images
Patch Scan	Region-of-interest scanning
TX-Scan	Through-transmission imaging
Concurrent PE/TX	Simultaneous pulse-echo & transmission
Dual Gate	Multi-layer gating
SALI & SALI Groups	Multi-zone inspection
D-Scan	Depth-selective imaging
SOFTWARE ODIS INSPECTION & ANALYSIS FEATURES	
User modes	■ Basic (user friendly) ■ Advanced (detailed analysis) ■ Production (automated scanning) ■ Offline Analysis (virtual scanning)
3D Imaging	Full volumetric reconstruction
Off-line Analysis	Virtual scanning & post-collection review on any computer

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